Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
KP-2012SRC-PRV	Super Bright Red (GaAlAs)	Water Clear	55	100	120°

- 1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value. 2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Super Bright Red	660		nm	IF=20mA
λD [1]	Dominant Wavelength	Super Bright Red	640		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Super Bright Red	20		nm	IF=20mA
С	Capacitance	Super Bright Red	45		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Super Bright Red	1.85	2.5	V	IF=20mA
lR	Reverse Current	Super Bright Red		10	uA	V _R =5V

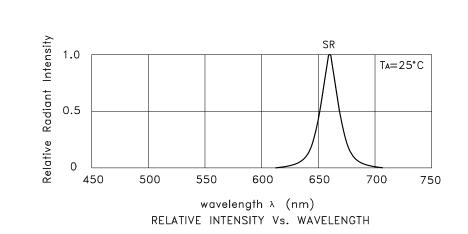
- 1.Wavelength: +/-1nm. 2. Forward Voltage: +/-0.1V.

Absolute Maximum Ratings at TA=25°C

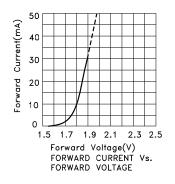
Absolute Maximum Ratings at TA-20 0					
Parameter	Super Bright Red	Units			
Power dissipation	75	mW			
DC Forward Current	30	mA			
Peak Forward Current [1]	155	mA			
Reverse Voltage	5	V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

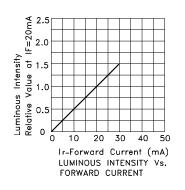
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

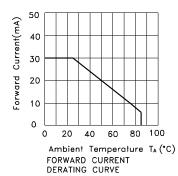
SPEC NO: DSAB1451 **REV NO: V.13** DATE: SEP/29/2010 PAGE: 2 OF 5 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: J.Yu ERP: 1203000177

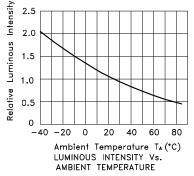


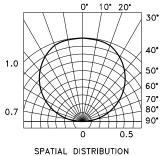
Super Bright Red KP-2012SRC-PRV











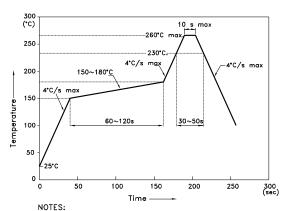
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KP-2012SRC-PRV

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



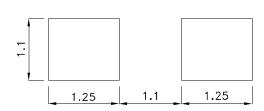
- NOTES:

 1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

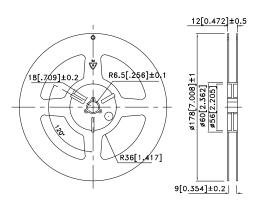
 2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

 3.Number of reflow process shall be 2 times or less.

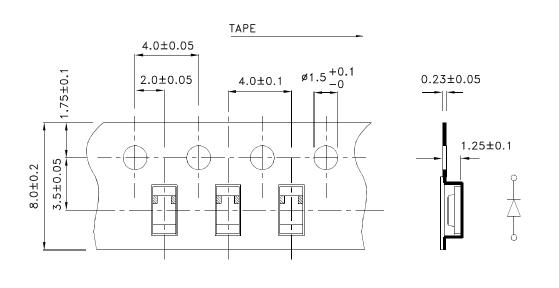
Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



Reel Dimension



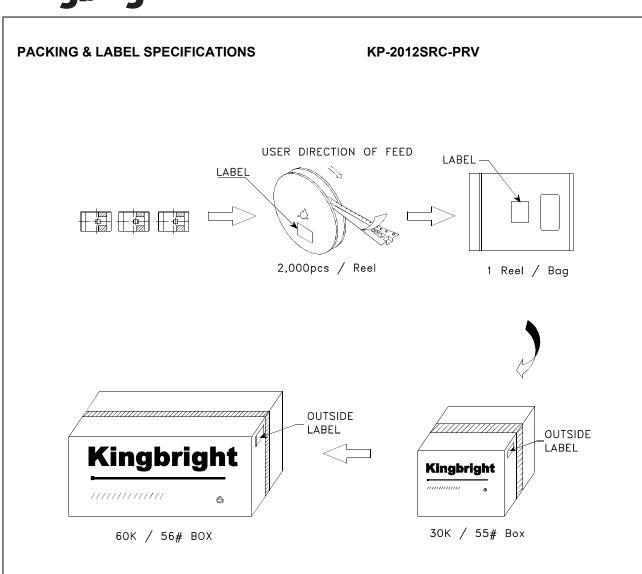
Tape Dimensions (Units : mm)

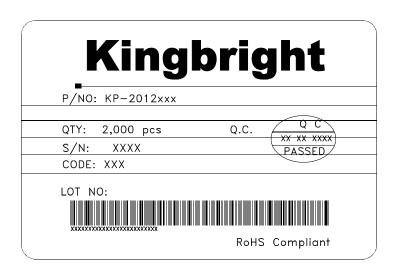


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